FOR IMMEDIATE RELEASE

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AEHR TEST SYSTEMS RECEIVES FIRST WAFER-LEVEL BURN-IN ORDER

Fremont, CA (June 7, 2001) – Aehr Test Systems (Nasdaq: AEHR), a leading provider of burn-in and parallel test solutions for DRAMs and other integrated circuits, today announced it has received its first wafer-level burn-in order. The order is for a full-wafer contactor for laser diodes, which will be used in a wafer-level burn-in system, and represents the first phase of a development partnership between Aehr Test and a manufacturer of VCSELs, or vertical cavity surface emitting lasers.

VCSELs are used in high-speed local-area data communications, and represent the latest technology in semiconductor laser diodes. The market for semiconductor lasers is projected by industry analysts to have a compound annual growth rate of greater than 40% over the next few years.

"This is an opportunity for Aehr Test to penetrate the emerging market for test equipment for optical communications devices. Contacting thousands of laser diodes simultaneously on a gallium arsenide wafer will be a challenge, but we believe that burn-in at the wafer level can offer manufacturers a significant cost saving advantage. We anticipate that the success of the first phase of this partnership will lead to follow-on orders for wafer-level systems and contactors for VCSEL wafer burn-in," said CJ Meurell, president and chief operating officer of Aehr Test. "Delivery of the first product resulting from this partnership is scheduled for the first half of calendar 2002," Meurell added.

In January of this year, Aehr Test completed a $6.5 million multi-year research and development agreement with the U.S. Defense Advanced Research Projects Agency (DARPA) to develop a Wafer-Level Burn-in and Test system for memories and other ICs. Wafer-level burn-in and test enables lower cost production of Known-Good Die (KGD) for multi-chip modules and systems-in-a-package.

"We are excited about this order because it uses our most advanced fine-pitch interconnect technology for contacting the wafer. We look at this as the first step in expanding our burn-in and test solutions to the wafer level for devices such as memories and microprocessors," said Rhea Posedel, chairman and chief executive officer of Aehr Test.

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Aehr Test will be introducing its Wafer-Level Burn-in product line at Semicon West, July 18-20, 2001, at the San Jose Convention Center in San Jose, CA. Those interested in a demonstration of the Wafer-Level Burn-in system should contact Chris Noe at Aehr Test (510-623-9400), or register through Aehr Test's web site (www.aehr.com), prior to Semicon West.

About Aehr Test Systems

Headquartered in Fremont, California, Aehr Test Systems is a leading provider of systems for burning-in and testing DRAM and logic integrated circuits and has an installed base of more than 2,000 systems worldwide. Aehr Test has developed and introduced three innovative products, the MTX and MAX3 systems and the DiePak® carrier. The MTX is a massively parallel test system designed to reduce the cost of memory testing by performing both test and burn-in on thousands of devices simultaneously. The MAX3 can effectively burn-in and functionally test sophisticated devices, such as digital signal processors, microprocessors, microcontrollers and systems-on-a-chip. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of bare die.

Safe Harbor Statement

This release contains forward-looking statements that involve risks and uncertainties relating to projections regarding industry growth and customer demand for the Company's products. Actual results may vary from projected results. These risks and uncertainties include economic conditions in Asia and elsewhere, acceptance by customers of the MTX, MAX and DiePak technologies, the Company's development and manufacture of a commercially successful wafer-level burn-in system, and the potential emergence of alternative technologies, which could adversely affect demand for the Company's products in fiscal year 2002. See the Company's 10-K and 10-Q reports filed with the SEC for additional risks affecting the Company.

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